

L Number	Hits	S arch Text	DB	Time stamp
-	2	semiconductor and ((insulating r di lectric) adj substrat) and sold r and land and (bonding adj pad) and resin and (wire or wiring) and (pr b or prob d or pr bing) and tester and capillary	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/12 16:40
-	147	(wire or wiring) adj (bond or bonding) adj structure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/12 16:40
-	14	((wire or wiring) adj (bond or bonding) adj structure) and pad and land	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/12 16:41
-	5	((((wire or wiring) adj (bond or bonding) adj structure) and pad and land) and (strength or strong or stronger)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/12 16:42
-	4	(((((wire or wiring) adj (bond or bonding) adj structure) and pad and land) and (strength or strong or stronger)) and (probe or probed or probing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/12 16:43
-	11267	pad and land	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/12 16:43
-	848	(pad and land) and (probe or probed or probing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/12 16:43
-	377	((pad and land) and (probe or probed or probing)) and (wire or wiring) and (bond or bonding or bonded)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/12 16:44
-	44	((((pad and land) and (probe or probed or probing)) and (wire or wiring) and (bond or bonding or bonded)) and capillary	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/12 16:44
-	13	(((((pad and land) and (probe or probed or pr bing)) and (wire or wiring) and (b nd r bonding or bonded)) and capillary) and test r	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/12 16:47

-	1757	bonding adj region	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/12 16:47
-	0	(bonding adj region) and (probe adj contact adj region)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/12 16:49
-	288	(bonding adj region) and (bonding adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/12 16:49
-	12	((bonding adj region) and (bonding adj pad)) and (probe or probed or probing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/12 16:51
-	240	(bonding adj pad) and land and (bonding adj wire)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/12 16:52
-	45	((bonding adj pad) and land and (bonding adj wire)) and (probe or probed or probing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/12 16:52
-	39	((((bonding adj pad) and land and (bonding adj wire)) and (probe or probed or probing)) and (test or tested or testing or tester)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:00
-	12	probe adj contact adj region	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 10:19
-	6186	probe adj contact	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 10:20
-	3	(probe adj contact) and bonding adj region	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 10:20

-	7044	prob adj (contact r r gi n)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 10:20
-	5	(prob adj (contact or region)) and (bonding adj region)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 10:21
-	15427	((bond or bonding) adj (wire or wiring)).ti,clm,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 10:23
-	333	((((bond or bonding) adj (wire or wiring)).ti,clm,ab.) and land	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 10:37
-	203	(((((bond or bonding) adj (wire or wiring)).ti,clm,ab.) and land) and (solder or bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 10:34
-	10	(((((bond or bonding) adj (wire or wiring)).ti,clm,ab.) and land) and (solder or bump)) and (probe or probing or probed).ti,clm,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 10:35
-	33	(((((bond or bonding) adj (wire or wiring)).ti,clm,ab.) and land) and ((wire or wiring) near10 (strength or strong or stronger))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 10:38
-	20	(((((bond or bonding) adj (wire or wiring)).ti,clm,ab.) and land) and ((wire or wiring) near5 (strength or strong or stronger))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 10:39
-	2	probe and tester and land and capillary and (insulating adj substrate) and (bonding adj pad) and ((bond or bonding) adj (wire or wiring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:02
-	6	probe and tester and land and (insulating adj substrate) and (bonding adj pad) and ((bond or bonding) adj (wire or wiring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:05

-	11	probe and land and (insulating adj substrate) and (bonding adj pad) and ((bond or bonding) adj (wire or wiring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:08
-	71	probe and land and (bonding adj pad) and ((bond or bonding) adj (wire or wiring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:18
-	13986	((bond or bonding) adj (wire or wiring)).ti,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:19
-	319	((((bond or bonding) adj (wire or wiring)).ti.) and (bonding adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:20
-	3	(((((bond or bonding) adj (wire or wiring)).ti.) and (bonding adj pad)) and (probe or probed or probing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:20
-	15427	((bond or bonding) adj (wire or wiring)).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:21
-	2624	((((bond or bonding) adj (wire or wiring)).ti,ab,clm.) and (bonding adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:21
-	105	(((((bond or bonding) adj (wire or wiring)).ti,ab,clm.) and (bonding adj pad)) and (probe or probed or probing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:21
-	20	(((((bond or bonding) adj (wire or wiring)).ti,ab,clm.) and (bonding adj pad)) and (probe or probed or probing)) and land	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:22
-	2	((((bond or bonding) adj (wire or wiring)).ti.) and (bonding adj pad) and land	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:26

-	319	(((b nd r bonding) adj (wir or wiring)).ti.) and (bonding adj pad)	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:26
-	2	(((bond or bonding) adj (wire or wiring)).ti.) and (bonding adj pad) and (insulating adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:27
-	49	(((bond or bonding) adj (wire or wiring)).ti,clm.) and (bonding adj pad) and (insulating adj substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:30
-	5	(((bond or bonding) adj (wire or wiring)).ti,clm.) and (bonding adj pad) and (insulating adj substrate) and (probe or probed or probing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:32
-	39	(((bond or bonding) adj (wire or wiring)).ti,clm.) and (bonding adj pad) and (insulating adj substrate) and (probe or probed or probing or contact)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:33
-	17	(((bond or bonding) adj (wire or wiring)).ti,clm.) and (bonding adj pad) and (insulating adj substrate) and (probe or probed or probing or contact) and (test or tester or tested or testing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:35
-	2	(((bond or bonding) adj (wire or wiring)).ti,clm,ab.) and (bonding adj pad) and (insulating adj substrate) and (probe or probed or probing or contact) and ((test or tester or tested or testing).ti,ab,clm.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:36
-	485	(((bond or bonding) adj (wire or wiring)).ti,clm,ab.) and ((test or tester or tested or testing).ti,ab,clm.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 11:38
-	31	(((bond or bonding) adj (wire or wiring)).ti,clm,ab.) and ((test or tester or tested or testing).ti,ab,clm.)) and land	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 13:56
-	60	(test or tester or tested or testing) and (probe or probed or probing or contact) and (bonding adj pad) and ((bonding or bond) adj (wire or wiring)) and (wire r wiring) and land and (s lder or bump) and waf r and (m ld r molding r m lded or r sin or epoxy) and (insulating or dielectric) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:01

-	7	((test or t st r or test d or testing) and (pr b or prob d or probing or c ntact) and (b nding adj pad) and ((bonding r b nd) adj (wire r wiring)) and (wire or wiring) and land and (solder or bump) and wafer and (mold r molding r m ld d or r sin r epoxy) and (insulating or dielectric) and substrate) and ((wire or wiring) near10 (strength or strong or stronger))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:01
-	6	((test or tester or tested or testing) and (probe or probed or probing or contact) and (bonding adj pad) and ((bonding or bond) adj (wire or wiring)) and (wire or wiring) and land and (solder or bump) and wafer and (mold or molding or molded or resin or epoxy) and (insulating or dielectric) and substrate) and (probe adj contact)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:02
-	60	((test or tester or tested or testing) and (probe or probed or probing or contact) and (bonding adj pad) and ((bonding or bond) adj (wire or wiring)) and (wire or wiring) and land and (solder or bump) and wafer and (mold or molding or molded or resin or epoxy) and (insulating or dielectric) and substrate) and land	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:02
-	48	((test or tester or tested or testing) and (probe or probed or probing or contact) and (bonding adj pad) and ((bonding or bond) adj (wire or wiring)) and (wire or wiring) and land and (solder or bump) and wafer and (mold or molding or molded or resin or epoxy) and (insulating or dielectric) and substrate) and ((bond or bonding or wire or wiring).clm,ti,ab.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:03
-	39	((test or tester or tested or testing) and (probe or probed or probing or contact) and (bonding adj pad) and ((bonding or bond) adj (wire or wiring)) and (wire or wiring) and land and (solder or bump) and wafer and (mold or molding or molded or resin or epoxy) and (insulating or dielectric) and substrate) and ((bond or bonding or wire or wiring).clm,ti,ab.)) and ((pad).clm,ti,ab.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:09
-	5069	land near10 (wire or wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:09
-	750	(land near10 (wir or wiring)) and ((wir or wiring) near10 pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:11

-	366	((land n ar10 (wir or wiring)) and ((wire or wiring) n ar10 pad)) and ((wir or wiring) n ar10 (s ld r r bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:12
-	124	((((land n ar10 (wir or wiring)) and ((wire r wiring) near10 pad)) and ((wire or wiring) near10 (solder or bump))) and ((probe or contact) near10 pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:13
-	50	(((((land near10 (wire or wiring)) and ((wire or wiring) near10 pad)) and ((wire or wiring) near10 (solder or bump))) and ((probe or contact) near10 pad)) and (test or tester or tested or testing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:21
-	1831	257/786	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:22
-	617	257/786 and (bonding adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:24
-	292	(257/786 and (bonding adj pad)) and ((bond or bonding) adj (wire or wiring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:24
-	22	((257/786 and (bonding adj pad)) and ((bond or bonding) adj (wire or wiring))) and land	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:24
-	847	257/786 and ((bond or bonding) adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:24
-	403	(257/786 and ((bond or bonding) adj pad)) and ((bond or bonding) adj (wire or wiring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:24
-	30	((257/786 and ((bond or bonding) adj pad)) and ((bond or bonding) adj (wire or wiring))) and land	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:24

-	673	((b nd r bonding) adj pad) near ((bond r b nding) adj (wir r wiring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:26
-	1	((b nd or b nding) adj pad) n ar ((b nd or bonding) adj (wire or wiring)) near land	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:27
-	1	((bond or bonding) adj pad) near ((bond or bonding) adj (wire or wiring)) near5 land	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:27
-	1	((bond or bonding) adj pad) near ((bond or bonding) adj (wire or wiring)) near10 land	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:28
-	2	((bond or bonding) adj pad) near ((bond or bonding) adj (wire or wiring)) near10 (land or landing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:29
-	4	((bond or bonding) adj pad) near ((bond or bonding) adj (wire or wiring)) same (land or landing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:31
-	66	(pad near (wire or wiring)) same (land or landing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:31
-	30	((pad near (wire or wiring)) same (land or landing)) and (probe or probed or probing or test or tested or testing or tester)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:32
-	9	((pad near (wire or wiring)) same (land or landing)) and (pad near (probe or probed or probing or test or tested or testing or tester or contact))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:33
-	48	((pad near (wire or wiring)) same (land or landing)) and (probe or probed or probing or test or tested or testing or tester or contact)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:39

-	124	(strength or strong or stronger) near ((bond or bonding) adj (wire or wiring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:40
-	109	(strength or strong or stronger) adj ((bond or bonding) adj (wire or wiring))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:44
-	0	((strength or strong or stronger) adj ((bond or bonding) adj (wire or wiring))) and (probe or probed or probing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:41
-	25	((strength or strong or stronger) adj ((bond or bonding) adj (wire or wiring))) and (test or tested or testing or tester)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:43
-	24	((strength or strong or stronger) adj ((bond or bonding) adj (wire or wiring))) and ((bond or bonding) adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:43
-	5	((strength or strong or stronger) adj ((bond or bonding) adj (wire or wiring))) and ((bond or bonding) adj pad) and (test or tested or testing or tester)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:43
-	1840	((bond or bonding) adj (wire or wiring)) and ((bond or bonding) adj pad) and (test or tester or tester or tested)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:45
-	233	((bond or bonding) adj (wire or wiring)) and ((bond or bonding) adj pad) and (test or tester or tester or tested)) and (land or landing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:46
-	206	((bond or bonding) adj (wire or wiring)) and ((bond or bonding) adj pad) and (test or tester or tester or tested)) and (land or landing)) and (resin or epoxy or encapsulant or encapsulated or encapsulating or mold or molding or molded)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:47
-	109	((bond or bonding) adj (wire or wiring)) and ((bond or bonding) adj pad) and (test or test or test or tested)) and (land or landing)) and (resin or epoxy or encapsulant or encapsulated or encapsulating or mold or molding or molded)) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:51

-	183	(solder or bump) and (land or landing or lead) and ((bond or bonding) adj pad) and (wire or wiring) and (probe or probed or probed or probing or contact) and wafer and (probe adj card) and (test or tested or testing or tester)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:55
-	151	((solder or bump) and (land or landing or lead) and ((bond or bonding) adj pad) and (wire or wiring) and (probe or probed or probing or contact) and wafer and (probe adj card) and (test or tested or testing or tester)) and (insulating or dielectric)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 14:55
-	140	((solder or bump) and (land or landing or lead) and ((bond or bonding) adj pad) and (wire or wiring) and (probe or probed or probing or contact) and wafer and (probe adj card) and (test or tested or testing or tester)) and (insulating or dielectric)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:02
-	1094	((bonding or bonding) adj pad) near (test or testing or tester or tested or probe or probed or probing or contact or contacted or contacting)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:04
-	2414	((bonding or bonding) adj pad) near (wire or wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:05
-	120	((bonding or bonding) adj pad) near (test or testing or tester or tested or probe or probed or probing or contact or contacted or contacting)) and ((bonding or bonding) adj pad) near (wire or wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:07
-	101	((bonding or bonding) adj pad) near (test or testing or tester or tested or probe or probed or probing or contact or contacted or contacting)) and ((bonding or bonding) adj pad) near (wire or wiring)) and (pad.ti,clm,ab.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:18
-	0	((bonding or bonding) adj pad) near (test or testing or tester or tested or probe or probed or probing or contact or contacted or contacting)) and ((bonding or bonding) adj pad) near (wire or wiring)) and (pad.ti,clm,ab.) and umehara	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:08
-	0	((bonding or bonding) adj pad) near (test or testing or tester or tested or probe or probed or probing or contact or contacted or contacting)) and ((bonding or bonding) adj pad) near (wire or wiring)) and (pad.ti,clm,ab.) and umeda	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:08

-	0	(((b nding or b nding) adj pad) n ar (t st r testing or test r or tested or prob or prob d r probing or contact or contact d r c ntacting)) and ((bonding or b nding) adj pad) near (wire or wiring)) and (pad.ti,clm,ab.)) and n tiy	USPAT; US-PGPUB; EP ; JPO; DERWENT; IBM_TDB	2002/08/13 15:09
-	0	(((bonding or bonding) adj pad) near (test or testing or tester or tested or probe or probed or probing or contact or contacted or contacting)) and ((bonding or bonding) adj pad) near (wire or wiring)) and (pad.ti,clm,ab.)) and norito	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:09
-	0	(((bonding or bonding) adj pad) near (test or testing or tester or tested or probe or probed or probing or contact or contacted or contacting)) and ((bonding or bonding) adj pad) near (wire or wiring)) and (pad.ti,clm,ab.)) and yoshikatsu	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:09
-	40	(((bonding or bonding) adj pad) near (test or testing or tester or tested or probe or probed or probing or contact or contacted or contacting)) and ((bonding or bonding) adj pad) near (wire or wiring)) and (pad.ti,clm,ab.)) and "257"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:10
-	13	(((bonding or bonding) adj pad) near (test or testing or tester or tested or probe or probed or probing or contact or contacted or contacting)) and ((bonding or bonding) adj pad) near (wire or wiring)) and (pad.ti,clm,ab.)) and "257") and (solder or bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:12
-	1	5925935.URPN.	USPAT	2002/08/13 15:14
-	4	("5300815" "5444303" "5569964" "5796171").PN.	USPAT	2002/08/13 15:14
-	0	5838071.URPN.	USPAT	2002/08/13 15:15
-	11	("3787966" "4067039" "4080485" "4845543" "4907734" "5060051" "5101263" "5172212" "5455461" "5495667" "5525839").PN.	USPAT	2002/08/13 15:15
-	32	(((bonding or bonding) adj pad) near (test or testing or tester or tested or probe or probed or probing or contact or contacted or contacting)) and ((bonding or bonding) adj pad) near (wire or wiring)) and (pad.ti,clm,ab.)) and (solder or bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:20
-	0	6392291.URPN.	USPAT	2002/08/13 15:18
-	5	("6048755" "6097087" "6118179" "6180504" "6232147").PN.	USPAT	2002/08/13 15:18
-	1	6112969.URPN.	USPAT	2002/08/13 15:19

-	3505	((b nd or bonding) adj pad) near (wire or wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:21
-	1732	((((bond r bonding) adj pad) n ar (wir or wiring)).clm,ti,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:23
-	114	(((((bond or bonding) adj pad) near (wire or wiring)).clm,ti,ab.) and (pad near (section or region or part)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:24
-	14	(((((bond or bonding) adj pad) near (wire or wiring)).clm,ti,ab.) and (pad near (section or region or part))) and (test or tested or testing or tester)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:51
-	12	norito near umehara	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 15:56
-	0	6380634.URPN.	USPAT	2002/08/13 15:52
-	16	("4928871" "5156323" "5205463" "5328079" "5623163" "5717252" "5842628" "5869905" "5884398" "5917235" "5961029" "5989995" "6010057" "6031281" "6068180" "6079610").PN.	USPAT	2002/08/13 15:52
-	0	6268644.URPN.	USPAT	2002/08/13 15:54
-	10	("5252783" "5304841" "5517056" "5596225" "5708294" "5723899" "5812381" "5982625" "5986333" "6093959").PN.	USPAT	2002/08/13 15:54
-	1	6225703.URPN.	USPAT	2002/08/13 15:54
-	4	("4994895" "5493153" "5814883" "5864175").PN.	USPAT	2002/08/13 15:55
-	0	628997.URPN.	USPAT	2002/08/13 15:56
-	3	yoshikatsu near umeda	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 16:00
-	0	2001338955.URPN.	USPAT	2002/08/13 15:58

-	2	(strong r stronger r str ngth) n ar ((bond or bonding) adj pad) n ar wir	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 16:01
-	89	(strong or stronger or strength) n ar5 ((bond or bonding) adj pad) near5 wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 16:02
-	41	(strong or stronger or strength) near3 ((bond or bonding) adj pad) near3 wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 16:05
-	89	(strong or stronger or strength) near5 ((bond or bonding) adj pad) near5 wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 16:43
-	0	"09878944"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 16:32
-	1	"09/878944"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 16:32
-	4	((strong or stronger or strength) near10 ((bond or bonding) adj pad) near10 wire) and probe and tester	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 16:44
-	58	((strong or stronger or strength) near10 ((bond or bonding) adj pad) near10 wire) and (probe or probing or probed or contact) and (tester or test or tested or testing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 16:56
-	78	((strong or stronger or strength) same ((bond or bonding) adj pad) same wire) and probe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 16:52
-	74	((strong or stronger or strength) same ((bond or bonding) adj pad) same wire) and probe and (test or tester or tested or testing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 16:53

-	54	(((strong r stronger r str ngth) sam ((bond or bonding) adj pad) sam wire) and probe and (test or tester or test d or testing)) and (bump or s ld r)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 16:53
-	68	((strong or stronger or strength) near15 ((bond or bonding) adj pad) near15 wire) and (probe or probing or probed or contact) and (tester or test or tested or testing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 16:59
-	2	(((strong or stronger or strength) near15 ((bond or bonding) adj pad) near15 wire) and (probe or probing or probed or contact) and (tester or test or tested or testing)) and (land or landing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 16:58
-	22	((land or landing) near15 ((bond or bonding) adj pad) near15 wire) and (probe or probing or probed or contact) and (tester or test or tested or testing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 10:27
-	203	((bond or bonding) adj (pad) adj structure).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 10:37
-	21	(((bond or bonding) adj (pad) adj structure).ti.) and (probe or test or testing or tester or probing).ti,clm,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 10:38
-	307	((bond or bonding) adj (pad) adj structure).ti,clm,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 10:37
-	34	(((bond or bonding) adj (pad) adj structure).ti,clm,ab.) and (probe or test or testing or tester or probing).ti,clm,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 10:45
-	16	("4237379" "5315241" "5532614" "5554940" "5783868" "5785538" "5844317" "5914614" "6025737" "6068892" "6104087" "6133627" "6143355" "6150193" "6215196" "6259608" "2001/0001541").PN.	USPAT	2002/08/14 10:43
-	30214	(bond or bonding) adj pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 10:47

-	163	((b nd r bonding) adj pad) and (((b nd r b nding) adj pad) n ar (probe r pr bing r pr b d r test r t sting r test d or test r)) and ((bond r bonding) adj (wir r wiring))	USPAT; US-P PUB; EPO; JP ; DERWENT; IBM_TDB	2002/08/14 10:50
-	80	((b nd r bonding) adj pad) and (((bond or bonding) adj pad) near (probe or probing or probed or test or testing or tested or tester)) and ((bond or bonding) adj (wire or wiring)) and (bump or solder) and (insulating or dielectric) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 10:52
-	20	((bond or bonding) adj pad) and (((bond or bonding) adj pad) near (probe or probing or probed or test or testing or tested or tester)) and ((bond or bonding) adj (wire or wiring)) and (bump or solder) and (insulating or dielectric) and substrate and land	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 10:53
-	3	((bond or bonding) adj pad) and (((bond or bonding) adj pad) near (probe or probing or probed or test or testing or tested or tester) near (section or region or part))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 11:32
-	14	((bond or bonding) adj pad) and (((bond or bonding) adj pad) near (probe or probing or probed or test or testing or tested or tester) near5 (section or region or part))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 11:35
-	103	((bond or bonding) adj pad) and (((bond or bonding) adj pad) near5 (probe or probing or probed or test or testing or tested or tester) near5 (section or region or part))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 11:37
-	56	((bond or bonding) adj pad) and (((bond or bonding) adj pad) near5 (probe or probing or probed or test or testing or tested or tester) near5 (section or region or part)).clm,ti,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 11:44
-	9	(((bond or bonding) adj pad) and (((bond or bonding) adj pad) near5 (probe or probing or probed or test or testing or tested or tester) near5 (section or region or part)).clm,ti,ab.) and pad.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 11:43
-	54	(((bond or bonding) adj pad) and (((bond or bonding) adj pad) near5 (probe or probing or probed or test or testing or tested or tester) near5 (section or region or part)).clm,ti,ab.) and pad.ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 11:43
-	1	(((bond or bonding) adj pad) and (((bond or bonding) adj pad) near5 (pr b or probing r pr bed r test or t sting r test d r test r) n ar5 (s ction or region r part)).clm,ti,ab.) and pad.ab.) and land	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 11:44

-	2	(((b nd r b nding) adj pad) and (((b nd r bonding) adj pad) n ar5 (prob or probing or prob d r t st or t sting r tested r test r) n ar5 (s ction or r gi n or part)).clm,ti,ab.) and (land or landing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 11:44
-	12	((b nd r bonding) adj pad) and (((b nd r bonding) adj pad) near2 (probe or probing or probed or test or testing or tested or tester) near2 (section or region or part)).clm,ti,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 11:47
-	21	((bond or bonding) adj pad) and (((bond or bonding) adj pad) near3 (probe or probing or probed or test or testing or tested or tester) near3 (section or region or part)).clm,ti,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 11:50
-	38	((bond or bonding) adj pad) and (((bond or bonding) adj pad) near4 (probe or probing or probed or test or testing or tested or tester) near4 (section or region or part)).clm,ti,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 11:54
-	7	((bond or bonding) adj pad) and (((bond or bonding) adj pad) near (probe or probing or probed or test or testing or tested or tester) near10 (section or region or part)).clm,ti,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 11:55
-	70	((bond or bonding) adj pad) and (((bond or bonding) adj pad) near5 (probe or probing or probed or test or testing or tested or tester) near10 (section or region or part)).clm,ti,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 12:08
-	452	((bond or bonding) adj pad) and (((bond or bonding) adj pad) near (probe or probing or probed or test or testing or tested or tester))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 09:36
-	5	(((bond or bonding) adj pad) and (((bond or bonding) adj pad) near (probe or probing or probed or test or testing or tested or tester))) and ((wire or wiring) near (reliability or strength or strong or stronger))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 09:38
-	22	(((bond or bonding) adj pad) and (((bond or bonding) adj pad) near (probe or probing or probed or test or testing or tested or tester))) and ((wire or wiring) near5 (reliability or strength or strong or stronger))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 09:38
-	6	5891745.URPN.	USPAT	2002/08/15 09:40

-	23	("3822465" "4581706" "4845543" "4926238" "4951098" "5053700" "5057900" "5132772" "5150193" "5239447" "5263246" "5286927" "5296745" "5327834" "5334809" "5336649" "5342807" "5358904" "5391516" "5432807" "5506499" "5523697" "5554940").PN.	USPAT	2002/08/15 09:44
-	6	5891745.URPN.	USPAT	2002/08/15 09:47
-	6	("3795973" "5008727" "5089772" "5187020" "5241266" "5307010").PN.	USPAT	2002/08/15 09:57
-	13	5554940.URPN.	USPAT	2002/08/15 09:58
-	0	6369407.URPN.	USPAT	2002/08/15 10:00
-	4	("4951098" "5726500" "5891745" "6008061").PN.	USPAT	2002/08/15 10:00
-	0	6351405.URPN.	USPAT	2002/08/15 10:01
-	5	("5506499" "5799021" "5891745" "5896039" "5991232").PN.	USPAT	2002/08/15 10:01
-	25	4951098.URPN.	USPAT	2002/08/15 10:01
-	9	("3423822" "4467400" "4605944" "4633280" "4747076" "4779108" "4851862" "4896168" "4899174").PN.	USPAT	2002/08/15 10:04
-	0	6359342.URPN.	USPAT	2002/08/15 10:04
-	8	("4951098" "5239191" "5446310" "5473196" "5719449" "5923047" "5936260" "6034426").PN.	USPAT	2002/08/15 10:04
-	19	("3717800" "4223337" "4241360" "4403240" "4447857" "4990996" "5155577" "5442241" "5455460" "5473196" "5517127" "5554940" "5731709" "5783868" "5854513" "5856687" "5886414" "5923047" "6025733").PN.	USPAT	2002/08/15 10:05
-	0	6429675.URPN.	USPAT	2002/08/15 10:06
-	29	("3717800" "4223337" "4241360" "4403240" "4447857" "4951098" "4959706" "4990996" "5155577" "5342992" "5442740" "5455460" "5473196" "5506499" "5517127" "5554940" "5731709" "5783868" "5844312" "5854513" "5856687" "5886414" "5914614" "5923047" "5994152" "6025730" "6025733" "6091155" "6107111").PN.	USPAT	2002/08/15 10:06

-	29	("3717800" "4223337" "4241360" "4403240" "4447857" "4951098" "4959706" "4990996" "5155577" "5342992" "5442740" "5455460" "5473196" "5506499" "5517127" "5554940" "5731709" "5783868" "5844312" "5854513" "5856687" "5886414" "5914614" "5923047" "5994152" "6025730" "6025733" "6091155" "6107111").PN.	USPAT	2002/08/15 10:07
-	29	("3717800" "4223337" "4241360" "4403240" "4447857" "4951098" "4959706" "4990996" "5155577" "5342992" "5442740" "5455460" "5473196" "5506499" "5517127" "5554940" "5731709" "5783868" "5844312" "5854513" "5856687" "5886414" "5914614" "5923047" "5994152" "6025730" "6025733" "6091155" "6107111").PN.	USPAT	2002/08/15 10:10
-	0	6373143.URPN.	USPAT	2002/08/15 10:10
-	18	(US-5891745-\$ or US-6373143-\$ or US-6068892-\$ or US-5554940-\$ or US-6369407-\$ or US-6351405-\$ or US-6429675-\$ or US-6348742-\$ or US-6008061-\$ or US-4951098-\$ or US-6359342-\$ or US-6342402-\$ or US-5886414-\$ or US-5783868-\$ or US-5923047-\$ or US-5719449-\$ or US-6091155-\$).did. or (US-20020017729-\$).did.	USPAT; US-PGPUB	2002/08/15 10:11
-	2	((US-5891745-\$ or US-6373143-\$ or US-6068892-\$ or US-5554940-\$ or US-6369407-\$ or US-6351405-\$ or US-6429675-\$ or US-6348742-\$ or US-6008061-\$ or US-4951098-\$ or US-6359342-\$ or US-6342402-\$ or US-5886414-\$ or US-5783868-\$ or US-5923047-\$ or US-5719449-\$ or US-6091155-\$).did. or (US-20020017729-\$).did.) and land	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:15
-	17	((US-5891745-\$ or US-6373143-\$ or US-6068892-\$ or US-5554940-\$ or US-6369407-\$ or US-6351405-\$ or US-6429675-\$ or US-6348742-\$ or US-6008061-\$ or US-4951098-\$ or US-6359342-\$ or US-6342402-\$ or US-5886414-\$ or US-5783868-\$ or US-5923047-\$ or US-5719449-\$ or US-6091155-\$).did. or (US-20020017729-\$).did.) and (test r t sting or t st d or t st r)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:16

-	3	(((US-5891745-\$ or US-6373143-\$ r US-6068892-\$ or US-5554940-\$ r US-6369407-\$ or US-6351405-\$ or US-6429675-\$ r US-6348742-\$ or US-6008061-\$ r US-4951098-\$ or US-6359342-\$ r US-6342402-\$ or US-5886414-\$ or US-5783868-\$ or US-5923047-\$ or US-5719449-\$ or US-6091155-\$).did. or (US-20020017729-\$).did.) and (test or testing or tested or tester)) and reliability	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:18
-	4	(((US-5891745-\$ or US-6373143-\$ or US-6068892-\$ or US-5554940-\$ or US-6369407-\$ or US-6351405-\$ or US-6429675-\$ or US-6348742-\$ or US-6008061-\$ or US-4951098-\$ or US-6359342-\$ or US-6342402-\$ or US-5886414-\$ or US-5783868-\$ or US-5923047-\$ or US-5719449-\$ or US-6091155-\$).did. or (US-20020017729-\$).did.) and (test or testing or tested or tester)) and (strength or strong or stronger)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:20
-	4	((US-5891745-\$ or US-6373143-\$ or US-6068892-\$ or US-5554940-\$ or US-6369407-\$ or US-6351405-\$ or US-6429675-\$ or US-6348742-\$ or US-6008061-\$ or US-4951098-\$ or US-6359342-\$ or US-6342402-\$ or US-5886414-\$ or US-5783868-\$ or US-5923047-\$ or US-5719449-\$ or US-6091155-\$).did. or (US-20020017729-\$).did.) and (strength or strong or stronger)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:21
-	22	5,506,499	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:21
-	6	5891745.URPN.	USPAT	2002/08/15 10:30
-	23	("3822465" "4581706" "4845543" "4926238" "4951098" "5053700" "5057900" "5132772" "5150193" "5239447" "5263246" "5286927" "5296745" "5327834" "5334809" "5336649" "5342807" "5358904" "5391516" "5432807" "5506499" "5523697" "5554940").PN.	USPAT	2002/08/15 10:31
-	1	6068892.URPN.	USPAT	2002/08/15 10:32

-	16	("4237379" "5315241" "5532614" "5554940" "5783868" "5785538" "5844317" "5914614" "6025737" "6068892" "6104087" "6133627" "6143355" "6150193" "6215196" "6259608" "2001/0001541").PN.	USPAT	2002/08/15 10:32
-	0	6348742.URPN.	USPAT	2002/08/15 10:32
-	17	((connection or wire or wiring) adj pad) and ((test or probe or testing) adj pad)) and (land or landing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:37
-	103	((connection or wire or wiring) adj pad) and ((test or probe or testing) adj pad)) and ((bond or bonding) near pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:37
-	220	((connection or wire or wiring) adj pad) and ((test or probe or testing) adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:40
-	32	((connection or wire or wiring) adj pad) and ((test or probe or testing) adj pad)).clm,ab,ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:44
-	37	((connection or wire or wiring or mounting) adj pad) and ((test or probe or testing) adj pad)).clm,ab,ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:46
-	27	(bond or bonding) near (pad) near (test or testing of probe or probing) near (wire or wiring or connection)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:49
-	517	(bond or bonding) near5 (pad) near5 (test or testing of probe or probing) near5 (wire or wiring or connection)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:55
-	147	((bond or bonding) near5 (pad) near5 (test or testing of probe or probing) near5 (wire or wiring or connection)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:50
-	29	((bond or bonding) near2 (pad) near2 (test or testing of probe or probing) near2 (wire or wiring or connection)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:52

-	74	((bond r b nding) n ar3 (pad) near3 (test or t sting ot prob or pr bing) n ar3 (wir r wiring or connection)).ab.	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:53
-	203	(bond or bonding) near5 (pad) near5 (test or testing ot probe or probing) near5 (wire or wiring or connection).ab,ti,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/15 10:56
-	23	(US-5554940-\$ or US-6313541-\$ or US-5900643-\$ or US-4951098-\$ or US-5506499-\$ or US-5891745-\$ or US-6373143-\$ or US-6348742-\$ or US-6068892-\$ or US-5783868-\$ or US-6008061-\$ or US-5923047-\$ or US-6369407-\$ or US-6351405-\$ or US-6429675-\$ or US-6342402-\$ or US-5886414-\$ or US-5719449-\$ or US-6091155-\$ or US-6426531-\$).did. or (US-20010001541-\$ or US-20020017729-\$).did. or (US-5506499-\$).did.	USPAT; US-PGPUB; DERWENT	2002/08/22 17:06
-	20	((US-5554940-\$ or US-6313541-\$ or US-5900643-\$ or US-4951098-\$ or US-5506499-\$ or US-5891745-\$ or US-6373143-\$ or US-6348742-\$ or US-6068892-\$ or US-5783868-\$ or US-6008061-\$ or US-5923047-\$ or US-6369407-\$ or US-6351405-\$ or US-6429675-\$ or US-6342402-\$ or US-5886414-\$ or US-5719449-\$ or US-6091155-\$ or US-6426531-\$).did. or (US-20010001541-\$ or US-20020017729-\$).did. or (US-5506499-\$).did.) and probe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/22 17:16
-	8	((US-5554940-\$ or US-6313541-\$ or US-5900643-\$ or US-4951098-\$ or US-5506499-\$ or US-5891745-\$ or US-6373143-\$ or US-6348742-\$ or US-6068892-\$ or US-5783868-\$ or US-6008061-\$ or US-5923047-\$ or US-6369407-\$ or US-6351405-\$ or US-6429675-\$ or US-6342402-\$ or US-5886414-\$ or US-5719449-\$ or US-6091155-\$ or US-6426531-\$).did. or (US-20010001541-\$ or US-20020017729-\$).did. or (US-5506499-\$).did.) and pr be and ext rnal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/22 17:08
-	0	6369407.URPN.	USPAT	2002/08/22 17:11
-	4	("4951098" "5726500" "5891745" "6008061").PN.	USPAT	2002/08/22 17:12

-	0	resin n ar encapsulates near chipe n ar wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/22 17:17
-	0	resin near encapsulates near chip near wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/22 17:17
-	44	resin near5 encapsulates near5 chip near5 wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/22 17:20
-	7	(resin near5 encapsulates near5 chip near5 wire) and (test or tested or testing or probe or probing or probed)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/22 17:21